

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT3376649

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| SUBMISSION TYPE: | NEW ASSIGNMENT |
| NATURE OF CONVEYANCE: | ASSIGNMENT |
| CONVEYING PARTY DATA | |
| | |
| Name | Execution Date |
| MASAYA SEKI | 04/14/2015 |
| TETSUJI TOGAWA | 04/23/2015 |
| KENYA ITO | 04/23/2015 |
| RECEIVING PARTY DATA | |
| Name: | EBARA CORPORATION |
| Street Address: | 11-1, HANEDA ASAHI-CHO |
| Internal Address: | OHTA-KU |
| City: | TOKYO |
| State/Country: | JAPAN |
| Postal Code: | 144-8510 |
| PROPERTY NUMBERS Total: 1 | |
| | |
| Property Type | Number |
| Application Number: | 14643529 |
| CORRESPONDENCE DATA | |
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| ATTORNEY DOCKET NUMBER: | 720074 |
| NAME OF SUBMITTER: | JOHN K. WINN |
| SIGNATURE: | /John K. Winn/ |
| DATE SIGNED: | 06/01/2015 |
| Total Attachments: 3 | |
| source=720074-ExecutedAssignment#page1.tif | |
| source=720074-ExecutedAssignment#page2.tif | |

ASSIGNMENT

WHEREAS, WE

(1) Masaya SEKI of Ebara Corporation, 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo 144-8510, Japan,

(2) Tetsuji TOGAWA of Ebara Corporation, 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo 144-8510, Japan,

(3) Kenya ITO of Ebara Corporation, 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo 144-8510, Japan,,

hereinafter referred to as Assignor, have invented a certain invention entitled:

POLISHING APPARATUS AND POLISHING METHOD

for which invention an application (non-provisional) for a U.S. patent was filed on March 10, 2015, under U.S. Application No. 14/643,529, and

WHEREAS, Ebara Corporation, of 11-1, Haneda Asahi-cho, Ohta-ku, Tokyo 144-8510 Japan, hereinafter referred to as Assignee, is desirous of acquiring the entire right, title, and interest in, to, and under the invention described in the patent application, including the entire priority right derived from the application,

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged,

Assignor assigns and transfers to Assignee and Assignee's legal representatives, successors, and assigns the entire right, title, and interest in, to, and under the invention, the referenced patent application, other such applications (e.g., provisional applications, non-provisional applications, continuations, continuations-in-part, divisionals, reissues, reexaminations, national and regional phase applications, petty patent applications, and utility model applications) that may be filed in the U.S. and/or any country foreign to the U.S. on the invention, the patents that may issue thereon, and the patents as may be modified as the result of applicable procedures (e.g., supplemental examinations, ex parte reexaminations, inter partes reexaminations, inter partes reviews, post-grant reviews, and oppositions),

Assignor conveys to the Assignee the right to make applications in Assignee's own behalf for protection of the invention in the U.S. and countries foreign to the U.S. and to claim priority to the referenced patent application and other such applications that may be filed in the U.S. or any country foreign to the U.S. on the invention under the Patent Cooperation Treaty, the Paris Convention, and any other international arrangements,

In re Appln. of Seki et al.
Attorney Docket No. 720074

Assignor will not execute any writing or do any act conflicting with the terms of this assignment,

Assignor will at any time upon request, without further or additional consideration, but at the expense of the Assignee, execute such additional assignments and other writings and do such additional acts as the Assignee may deem necessary or desirable to pursue the patent applications identified herein, including, but not limited to, rendering all necessary assistance in making applications for and obtaining patents that may issue thereon in the U.S. and any countries foreign to the U.S. on the invention, and in enforcing any rights accruing as a result of such applications or patents, by, for example, executing statements and other affidavits,

Assignor and Assignee agree the terms of this assignment shall bind, and inure to the benefit of, the legal representatives, successors, and assigns of all parties hereto,

Assignor authorizes Assignee to insert in this assignment the number and filing date of the application if the number and filing date of the application are not recited herein at the time of execution of this assignment by any or all of the parties hereto,

Assignor and Assignee agree that U.S. law governs this assignment, and

Assignee acknowledges and accepts this assignment.

IN WITNESS WHEREOF, Assignor has hereunder set his/her hand on the date shown below.

Date 4.14.2015

Masaya Seki
Assignor: Masaya SEKI

Date April. 23. 2015

Yuu Ishii
Witness: Yu ISHII

Date April. 24. 2015

Masayuki Nakanishi
Witness: Masayuki NAKANISHI

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Date April. 23. 2015

T. Togawa
Assignor: Tetsuji TOGAWA

Date April. 23. 2015

Yu Ishii
Witness: Yu ISHII

Date April. 24. 2015

Masayuki Nakanishi
Witness: Masayuki NAKANISHI

Date April. 23. 2015

Kenya Ito
Assignor: Kenya ITO

Date April. 23. 2015

Yu Ishii
Witness: Yu ISHII

Date April. 24. 2015

Masayuki Nakanishi
Witness: Masayuki NAKANISHI